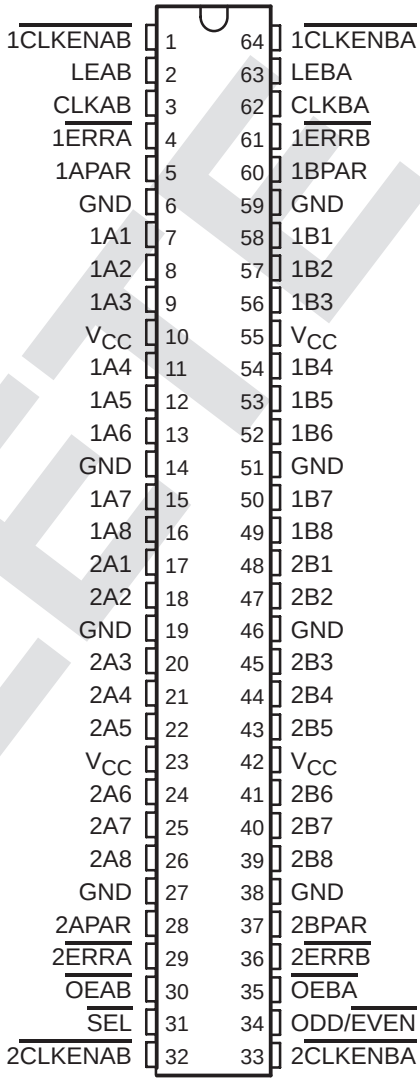
- **Member of the Texas Instruments *Widebus+*™ Family**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode**
- **Simultaneously Generates and Checks Parity**
- **Option to Select Generate Parity and Check or Feed-Through Data/Parity in A-to-B or B-to-A Directions**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Packaged in Thin Shrink Small-Outline (DGG) Package**

DGG PACKAGE
(TOP VIEW)



description

This 18-bit (dual-octal) noninverting registered transceiver is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74ALVC16901 is a dual 9-bit to dual 9-bit parity transceiver with registers. The device can operate as a feed-through transceiver or it can generate/check parity from the two 8-bit data buses in either direction.

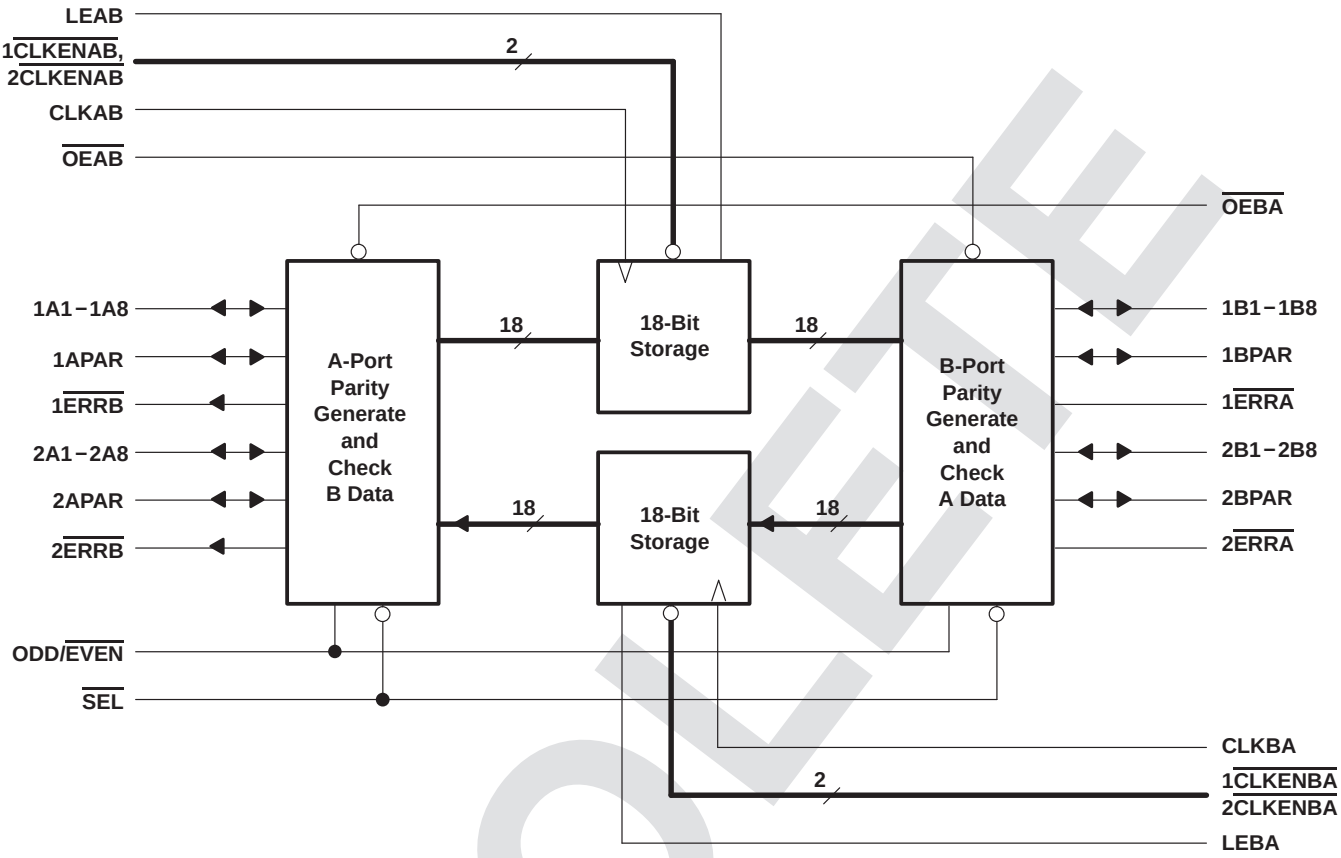
The SN74ALVC16901 features independent clock (CLKAB or CLKBA), latch-enable (LEAB or LEBA), and dual 9-bit clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) inputs. It also provides parity-enable ($\overline{\text{SEL}}$) and parity-select (ODD/$\overline{\text{EVEN}}$) inputs and separate error-signal ($\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$) outputs for checking parity. The direction of data flow is controlled by $\overline{\text{OEAB}}$ and $\overline{\text{OEBA}}$. When $\overline{\text{SEL}}$ is low, the parity functions are enabled. When $\overline{\text{SEL}}$ is high, the parity functions are disabled and the device acts as an 18-bit registered transceiver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVC16901 is available in TI's thin shrink small-outline (DGG) package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVC16901 is characterized for operation from −40°C to 85°C.

block diagram



FUNCTION TABLE†

INPUTS					OUTPUT
CLKENAB	OEAB	LEAB	CLKAB	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0‡
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B_0‡
L	L	L	H	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar, but uses OEBA, LEBA, and CLKENBA.
‡ Output level before the indicated steady-state input conditions were established
§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

PARITY-ENABLE FUNCTION TABLE

INPUTS			OPERATION OR FUNCTION	
$\overline{SEL}$	$\overline{OEBA}$	$\overline{OEAB}$		
L	H	L	Parity is checked on port A and is generated on port B.	
L	L	H	Parity is checked on port B and is generated on port A.	
L	H	H	Parity is checked on port B and port A.	
L	L	L	Parity is generated on port A and B if device is in FF mode.	
H	L	L	Parity functions are disabled; device acts as a standard 18-bit registered transceiver.	Q_A data to B, Q_B data to A
H	L	H		Q_B data to A
H	H	L		Q_A data to B
H	H	H		Isolation

PARITY FUNCTION TABLE

INPUTS								OUTPUTS			
$\overline{SEL}$	$\overline{OEBA}$	$\overline{OEAB}$	ODD/$\overline{EVEN}$	Σ OF INPUTS A1−A8 = H	Σ OF INPUTS B1−B8 = H	APAR	BPAR	APAR	$\overline{ERRA}$	BPAR	$\overline{ERRB}$
L	H	L	L	0, 2, 4, 6, 8	N/A	L	N/A	N/A	H	L	Z
L	H	L	L	1, 3, 5, 7	N/A	L	N/A	N/A	L	H	Z
L	H	L	L	0, 2, 4, 6, 8	N/A	H	N/A	N/A	L	L	Z
L	H	L	L	1, 3, 5, 7	N/A	H	N/A	N/A	H	H	Z
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	L	L	Z	N/A	H
L	L	H	L	N/A	1, 3, 5, 7	N/A	L	H	Z	N/A	L
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	H	L	Z	N/A	L
L	L	H	L	N/A	1, 3, 5, 7	N/A	H	H	Z	N/A	H
L	H	L	H	0, 2, 4, 6, 8	N/A	L	N/A	N/A	L	H	Z
L	H	L	H	1, 3, 5, 7	N/A	L	N/A	N/A	H	L	Z
L	H	L	H	0, 2, 4, 6, 8	N/A	H	N/A	N/A	H	H	Z
L	H	L	H	1, 3, 5, 7	N/A	H	N/A	N/A	L	L	Z
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	L	H	Z	N/A	L
L	L	H	H	N/A	1, 3, 5, 7	N/A	L	L	Z	N/A	H
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	H	H	Z	N/A	H
L	L	H	H	N/A	1, 3, 5, 7	N/A	H	L	Z	N/A	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	H	Z	H
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	L	Z	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	L	Z	L
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	L	Z	L
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	H	Z	H
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	L	Z	L
L	L	L	L	N/A	N/A	N/A	N/A	PE†	Z	PE†	Z
L	L	L	H	N/A	N/A	N/A	N/A	PO‡	Z	PO‡	Z

† Parity output is set to the level so that the specific bus side is set to even parity.
‡ Parity output is set to the level so that the specific bus side is set to odd parity.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 4.6 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . −0.5 V to 4.6 V
Input voltage range, V_I (I/O ports) (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 3) . . . . . 1 W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V
		V_{CC} = 2.7 V to 3.6 V		0.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2.3 V		−12	mA
		V_{CC} = 2.7 V		−12	
		V_{CC} = 3 V		−24	
I_{OL}	Low-level output current	V_{CC} = 2.3 V		12	mA
		V_{CC} = 2.7 V		12	
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}†	T_A = −40°C to 85°C			UNIT
					MIN	TYP	MAX	
V_{OH}		I_{OH} = −100 μA		MIN to MAX	V_{CC} − 0.2			V
		I_{OH} = −6 mA,	V_{IH} = 1.7 V	2.3 V	2			
		I_{OH} = −12 mA	V_{IH} = 1.7 V	2.3 V	1.7			
			V_{IH} = 2 V	2.7 V	2.2			
			V_{IH} = 2 V	3 V	2.4			
		I_{OH} = −24 mA,	V_{IH} = 2 V	3 V	2			
V_{OL}		I_{OL} = 100 μA		MIN to MAX			0.2	V
		I_{OL} = 6 mA,	V_{IL} = 0.7 V	2.3 V			0.4	
		I_{OL} = 12 mA	V_{IL} = 0.7 V	2.3 V			0.7	
			V_{IL} = 0.8 V	2.7 V			0.4	
		I_{OL} = 24 mA,	V_{IL} = 0.8 V	3 V			0.55	
I_I		V_I = V_{CC} or GND		3.6 V			±5	μA
$I_{I(hold)}$		V_I = 0.7 V		2.3 V	45			μA
		V_I = 1.7 V			−45			
		V_I = 0.8 V		3 V	75			
		V_I = 2 V			−75			
		V_I = 0 to 3.6 V		3.6 V			±500	
I_{OZ}‡		V_O = V_{CC} or GND		3.6 V			±10	μA
I_{CC}		V_I = V_{CC} or GND,	I_O = 0	3.6 V			40	μA
ΔI_{CC}		V_{CC} = 3 V to 3.6 V, Other inputs at V_{CC} or GND	One input at V_{CC} − 0.6 V,				750	μA
C_i	Control inputs	V_I = V_{CC} or GND		3.3 V		3		pF
C_{io}	A or B ports	V_O = V_{CC} or GND		3.3 V		7.5		pF
C_o	Output ports	V_O = V_{CC} or GND		3.3 V		6		pF

† For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.
‡ For I/O ports, the paramter I_{OZ} includes the input-leakage current.

timing requirements over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	125	0	125	0	125	MHz
t_w	Pulse duration	CLK↑	3		3		3		ns
		LE high	3		3		3		
t_{su}	Setup time	APAR or BPAR before CLK↑	1.9		2		1.7		ns
		$\overline{\text{CLKEN}}$ before CLK↑	2.1		2.1		1.7		
		APAR or BPAR before LE↓	1.4		1.3		1.2		
t_h	Hold time	APAR or BPAR after CLK↑	0.4		0.4		0.5		ns
		$\overline{\text{CLKEN}}$ after CLK↑	0.5		0.5		0.7		
		APAR or BPAR after LE↓	0.9		1.1		0.9		

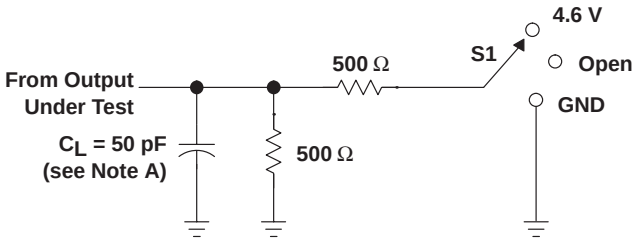
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			125		125		125		MHz
t_{pd}	A or B	B or A	1.5	5.8		4.8	1	4.4	ns
	A or B	BPAR or APAR	2.5	9.5		7.6	2	6.7	
	APAR or BPAR	BPAR or APAR	1.5	6.3		5.2	1	4.7	
	APAR or BPAR	$\overline{ERRA}$ or $\overline{ERRB}$	2.5	10.3		8.7	2	7.5	
	ODD/$\overline{EVEN}$	$\overline{ERRA}$ or $\overline{ERRB}$	2	9.3		7.9	1.5	6.8	
	ODD/$\overline{EVEN}$	BPAR or APAR	2	8.9		7.6	1.5	6.5	
	$\overline{SEL}$	BPAR or APAR	1.5	6.7		5.9	1	5.1	
	CLKAB or CLKBA	A or B	1.5	7		5.8	1	5.1	
	CLKAB or CLKBA	BPAR or APAR parity feedthrough	2	7.7		6.3	1.5	5.6	
	CLKAB or CLKBA	BPAR or APAR parity generated	3	10.8		8.7	2	7.7	
	CLKAB or CLKBA	$\overline{ERRA}$ or $\overline{ERRB}$	3	11.1		8.9	2	7.9	
	LEAB or LEBA	A or B	1.5	6.6		5.5	1	4.8	
	LEAB or LEBA	BPAR or APAR parity feedthrough	2	7.3		6	1.5	5.3	
	LEAB or LEBA	BPAR or APAR parity generated	3	10.4		8.3	2	7.4	
	LEAB or LEBA	$\overline{ERRA}$ or $\overline{ERRB}$	3	10.5		8.5	2	7.5	
t_{en}	$\overline{OEAB}$ or $\overline{OEBA}$	B, BPAR or A, APAR	1.5	6.8		6.1	1	5.3	ns
t_{dis}	$\overline{OEAB}$ or $\overline{OEBA}$	B, BPAR or A, APAR	2	6.3		5.2	1.5	4.9	ns
t_{en}	$\overline{OEAB}$ or $\overline{OEBA}$	$\overline{ERRA}$ or $\overline{ERRB}$	1.5	6.7		5.5	1	4.9	ns
t_{dis}	$\overline{OEAB}$ or $\overline{OEBA}$	$\overline{ERRA}$ or $\overline{ERRB}$	2	7.5		6.5	1	5.7	ns
t_{en}	$\overline{SEL}$	$\overline{ERRA}$ or $\overline{ERRB}$	1.5	7.2		6.5	1	5.5	ns
t_{dis}	$\overline{SEL}$	$\overline{ERRA}$ or $\overline{ERRB}$	2	6.6		5.4	1.5	4.9	ns

operating characteristics, T_A = 25°C

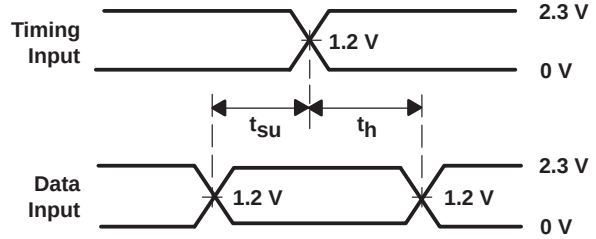
PARAMETER			TEST CONDITIONS	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 10 MHz	22	27	pF
		Outputs disabled		5	8	

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 2.5 V ± 0.2 V

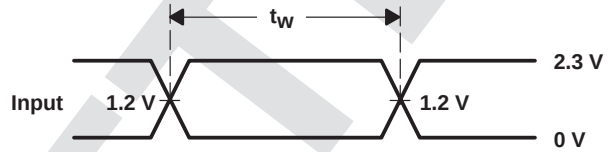


TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	4.6 V
t_{PHZ}/t_{PZH}	GND

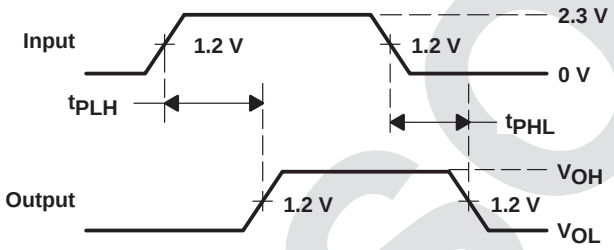
LOAD CIRCUIT



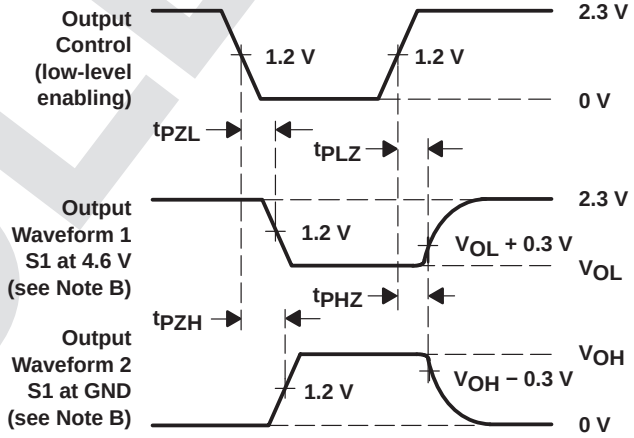
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

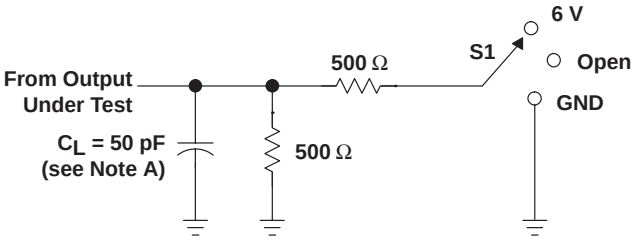


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

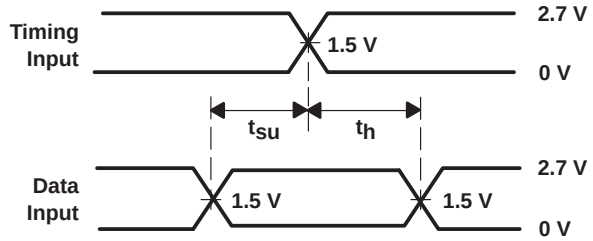
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 2.7 V AND 3.3 V ± 0.3 V

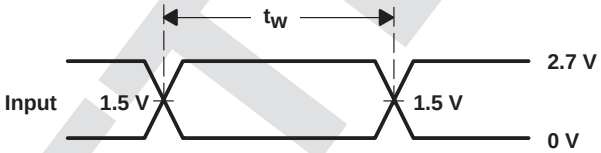


TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 6 V GND

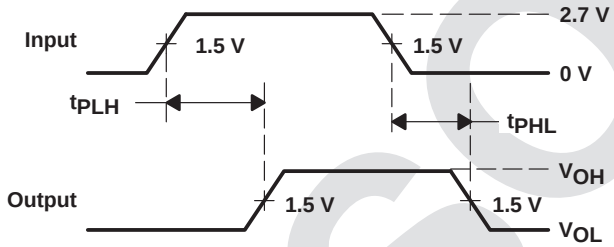
LOAD CIRCUIT



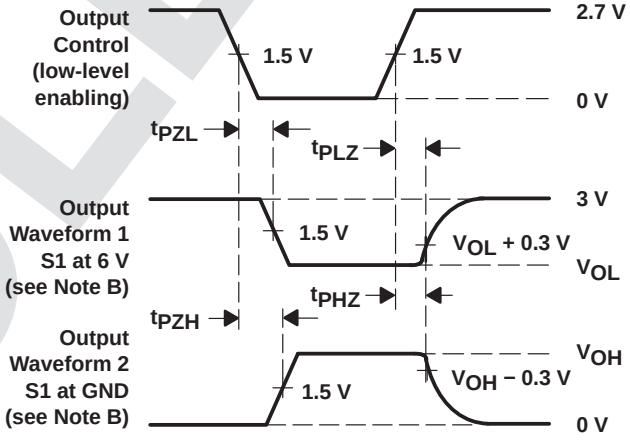
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms

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